



JGOLED-110 Series Pin Fin Sinks $\Phi 110\text{mm}$ for COB Modular Product Brief

Features VS Benefits

- * Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
- * Thermal resistance range R_{th} (1.47°C/W ; 1.14°C/W ; 1.0°C/W).
- * Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COB's:
- * Diameter 110mm - Standard height 50.0mm / 80.0mm / 100.0mm , Other heights on request.
- * Forged from highly conductive aluminum.
- 2 standard colors - clear anodised - black anodised
- Zhaga Book 3 Spot Light Modules Edison ,Xicato ,Bridgelux , Osram ,Citizen , Lumileds ,Cree , Tridonic , Vossloh-Schwabe ,Seoul ,LG ,Lustrous ,Prolight ,Samung ,SHARP , Luminus .Philips



- 1) Xicato XSM, XIM,XTM;(XSA-309;XSA-310)
- 2) Bridgelux ESS, ESR, Vero 10, Vero 13,Vero 18,Vero 29 V-series;
- 3) Citizen CLL024-CLU028, CLL034-CLU038,CLL044-CLU048;
- 4) Cree XLamp CXA13xx, CXA15xx,CXA18,CXA25;
- 5) Lumileds Luxeon COB's 1203, 1204, 1205, Luxeon K arrays K12, K16;
- 6) LG Innotek LEMWM18 27W, 24W, 40W;
- 7) Seoul Semiconductor ZC25, ZC40,ZC60, ZC100 Series;
- 8) Tridonic TALEXXmodule SLE Modules engines;
- 9) Luminus C##14 ,C##22COB LED engines.
- 10) Edison EdiLex SLM and EdiLex II COB LED engines;
- 11) GE lighting Infusion™ LED Modules.
- 12) Prolight Opto PABS, PABA, PACB, PANA;
- 13) SHARP Tiger Zenigataand and Mega Zenigata LED engines;
- 14) Samsung COB LC026B,LC033B,LC040BCOB LED engines;
- 15) Vossloh-Schwabe Vossloh-Schwabe LUGA Shop LED engines;
- 16) OSRAM PrevaLED Core,SOLERIQ P,SOLERIQ E and SOLERIQ S LED engines;
- 17) Lustrous M series, LUSTRON series, Coral series,LUSTRON 5 6 series LED engines;
- 18) Philips Fortimo SLM LED engines.

Order Information

Example:JGOLED-11050-B-#

Example:JGOLED-110 **1** - **2** - **3**

- 1** Hight (mm)
- 2** Anodising Color
- B-Black
- C-Clear
- Z-Custom
- 3** Mounting Options - see graphics for details Combinations available
- Ex.order code - 12
- means option 1 and 2 combined

Jaro Thermal recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, a thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.

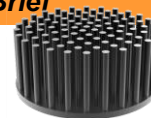
Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact Jaro Thermal.
- Jaro Thermal reserves the right to change products or specifications without prior notice.



JGOLED-110 Series Pin Fin Sinks $\Phi 110$ mm for COB Modular Product Brief

The product data table



Brand	Jaro Thermal		
Series Name	JGOLED star heat sinks		
Series Number	JGOLED-110		
Manufacturing Technology	Cold Forged		
Material	AL 1070		
Color & Finishing	Black Anodized		
Certification	CE, ROHS, WEEE		
Diameter(mm)	$\Phi 110$		
Height(mm)	50.0mm	80.0mm	100.0mm
Item Number	JGOLED-11050	JGOLED-11080	JGOLED-110100
Max. Lumen	4800 lm	6200 lm	6200 lm
Dissipated Power (Ths-amb,50°C)	34.0 W	44.0 W	50.0 W
Thermal Resistance Rth (°C/W)	1.47° C/W	1.14 °C/W	1.0 °C/W
Cooling Surface Area (mm²)	83372.0 mm²	129119.0 mm²	159593 mm²
Net Weight (g)	463.0 g	617.0 g	720.0 g
Quantity (pcs/CTN)	24 pcs	16 pcs	12 pcs
Modular Types	COB	COB	COB
For Environments	Indoor area		
For Lightings	Down lights,Architectural lights		
For Application	Retail & Hospitality,Mall & Food,Architectural & Museums,Office & Education, Station & Airport,Healthcare		
For LED brands	A dura,Bridgelux,BJB,Citizen,Cree,Edison,GE,LG,Lumileds,Lumens,Luminus,Ledil,Nichia, Osram,Philips,Prolight Opto,Samsung,Seoul,Sharp,Tridonic,Vossloh Schwabe,Xicato,Zhaga		

* 3D files are available in ParaSolid, STP and IGS on request

* The thermal resistance Rth is determined with a calibrated heat source of 14mm×14mm central placed on the heat sink, Tamb 40° and an open environment. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C
The thermal resistance of a LED cooler is not a fix value and will vary with the applied dissipated power Pd

* Dissipated power Pd. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C
The maximal dissipated power needs to be verified in function of required case temperature Tc or junction temperature Tj and related to the estimated ambient temperature where the light fixture will be placed
Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module

To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$

Pd - Dissipated power

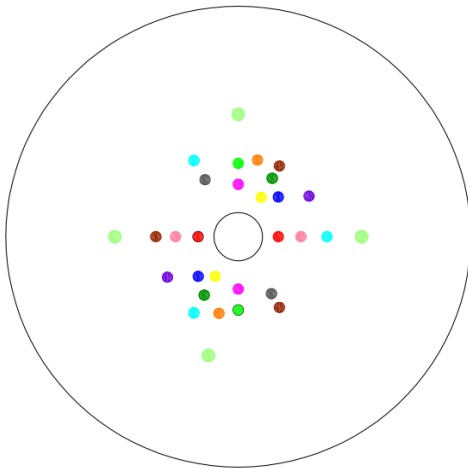
Pe - Electrical power

η_L = Light efficiency of the LED module

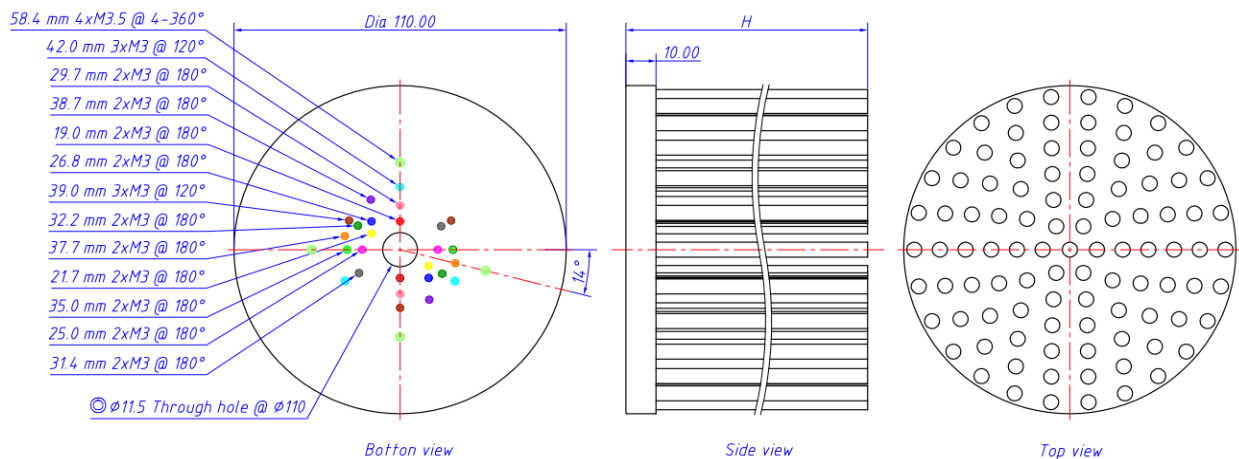


JGOLED-110 Series $\Phi 110\text{mm}$ Pin Fin Heat Sink Drawings

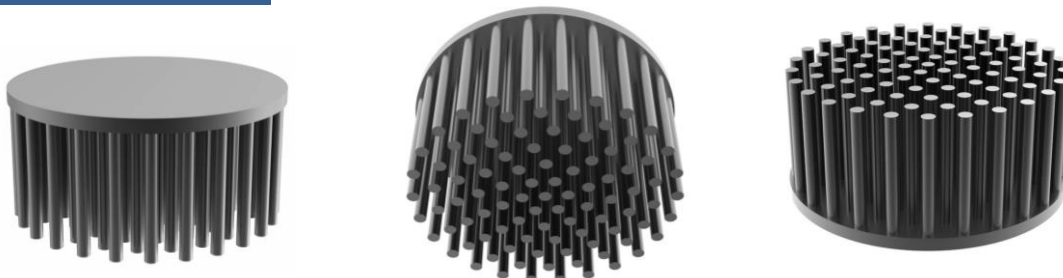
Drawings & Type Selection



No.	Finish	Mounting Hole
A1	Red	19.0 mm 2xM3 @ 180°
A2	Yellow	21.7 mm 2xM3 @ 180°
A3	Magenta	25.0 mm 2xM3 @ 180°
A4	Blue	26.8 mm 2xM3 @ 180°
A5	Pink	29.7 mm 2xM3 @ 180°
A6	Grey	31.4 mm 2xM3 @ 180°
A7	Green	32.2 mm 2xM3 @ 180°
A8	Light Green	35.0 mm 2xM3 @ 180°
A9	Orange	37.7 mm 2xM3 @ 180°
A10	Purple	38.7 mm 2xM3 @ 180°
A11	Brown	39.0 mm 3xM3 @ 120°
A12	Cyan	42.0 mm 3xM3 @ 120°
A13	Light Green	58.4mm 4xM3.5 @ 4-360°
A14		© $\Phi 11.5$ Through hole @ $\Phi 110.0$



Product display





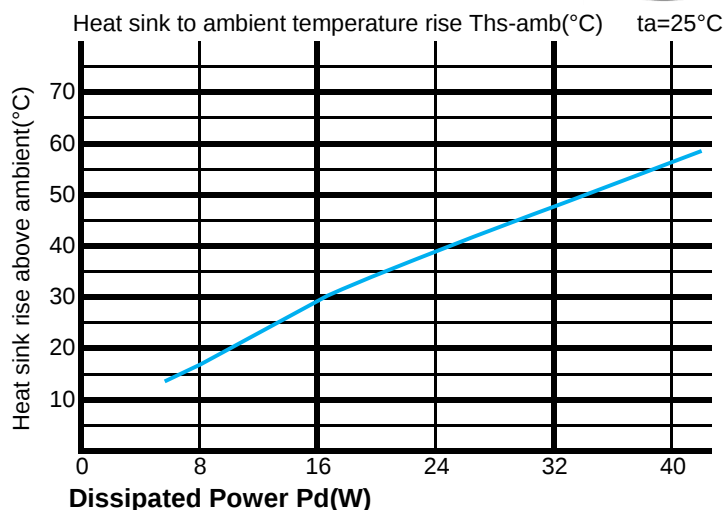
JGOLED-110 Series $\Phi 110\text{mm}$ Material AL1070 Pin Fin Heat Sinks Thermal Data

The thermal data table



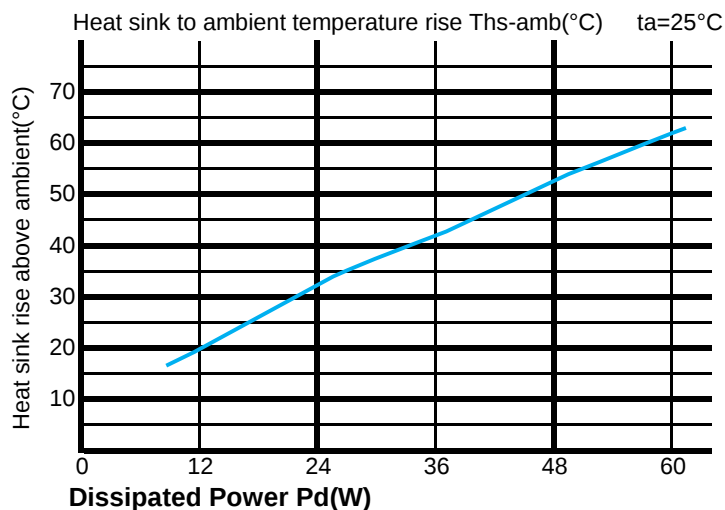
JGOLED-11050 thermal data

$P_d = P_e \times (1 - \eta_L)$ Dissipated Power $P_d(\text{W})$		Heat sink to ambient thermal resistance $R_{hs-amb} (^\circ\text{C/W})$	Heat sink to ambient temperature rise $T_{hs-amb} (^\circ\text{C})$
		JGOLED-11050	JGOLED-11050
Dissipated Power $P_d(\text{W})$	8	2.25	16
	16	1.81	29
	24	1.63	39
	32	1.5	48
	40	1.4	56



JGOLED-11080 thermal data

$P_d = P_e \times (1 - \eta_L)$ Dissipated Power $P_d(\text{W})$		Heat sink to ambient thermal resistance $R_{hs-amb} (^\circ\text{C/W})$	Heat sink to ambient temperature rise $T_{hs-amb} (^\circ\text{C})$
		JGOLED-11080	JGOLED-11080
Dissipated Power $P_d(\text{W})$	12	1.67	20
	24	1.36	33
	36	1.17	42
	48	1.1	53
	60	1.03	62





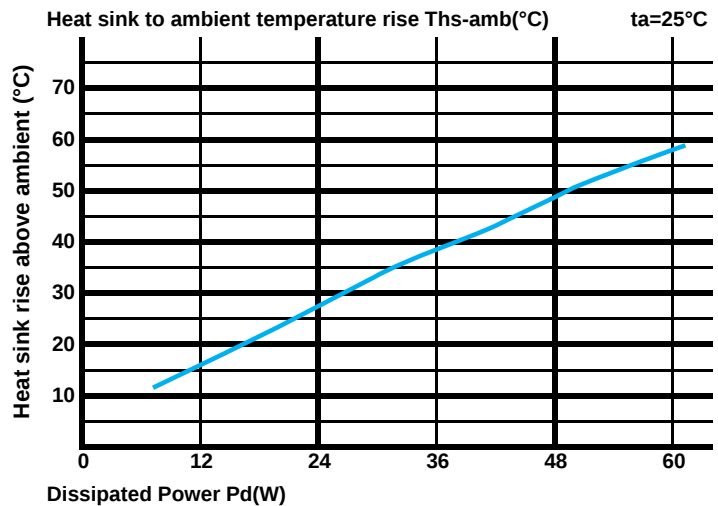
JGOLED-110 Series $\Phi 110\text{mm}$ Material AL1070 Pin Fin Heat Sinks Thermal Data

The thermal data table



JGOLED-110100 thermal data

Dissipated Power Pd(W)	Pd = Pe x (1-ηL) (1-ηL)	Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		JGOLED-110100	JGOLED-110100
12		1.67	20
24		1.36	33
36		1.17	42
48		1.1	53
60		1.03	62



* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

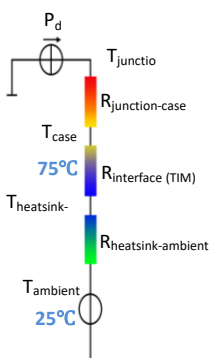
*To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$.

Pd - Dissipated power ; Pe - Electrical power ; η_L = Light efficiency of the LED module;

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

Jaro Thermal recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [°C/W] ; T_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer

shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface (TIM)}}$ [°C/W], the thermal resistance with the heat sink is $R_{\text{heatsink-ambient}}$ [°C/W], and the ambient temperature is T_{ambient} [°C].

*Thermal resistances outside the package $R_{\text{interface (TIM)}}$ and $R_{\text{heatsink-ambient}}$ can be integrated into the thermal resistance $R_{\text{case-ambient}}$ at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot P_d + T_{\text{ambient}}$$